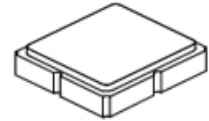


- Low-loss RF SAW Filter
- Miniature 3 x 3 mm SMD Package
- Complies with Directive 2002/95/EC (RoHS)
- AEC-Q200 Qualified
- Moisture Sensitivity Level: 1

RoHS  
Compliant

**SF2381E**

**2492 MHz  
SAW Filter**



**SM3030-6**

**Absolute Maximum Ratings**

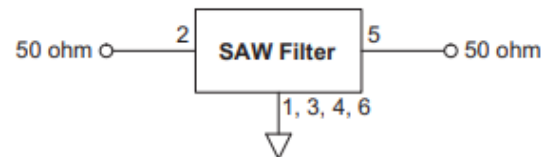
Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-grounded Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range	-40 to +85	°C
Maximum Soldering Profile, 2 cycles/10 seconds minimum	260	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_c$			2492		MHz
Insertion Loss, 2489.5 to 2494.5 MHz	IL			1.55	2.0	dB
Amplitude Ripple, 2489.5 to 2494.5 MHz				0.2	1.0	dB
VSWR, 2489.5 to 2494.5 MHz				1.2	1.8	
Attenuation, Referenced to 0 dB:						dB
DC to 2390 MHz			33	40		
2575 to 3000 MHz			43	50		
Source Impedance	$Z_s$			50		$\Omega$
Load Impedance	$Z_L$			50		$\Omega$
Temperature Coefficient of Frequency				-36		ppm/°C
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	6J, YWWS					
Standard Reel Quantity	Reel Size 7 inch					500 Pieces/Reel
	Reel Size 13 inch					3000 Pieces/Reel

**Electrical Connections**

Connection	Terminals
Input	2
Output	5
Case Ground	All others

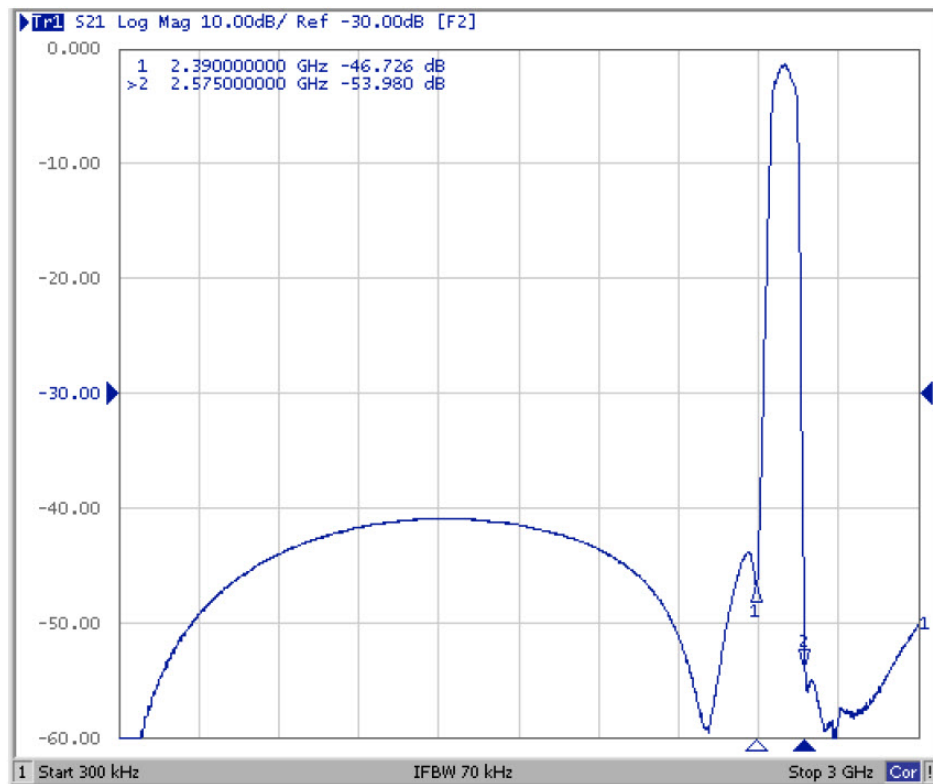
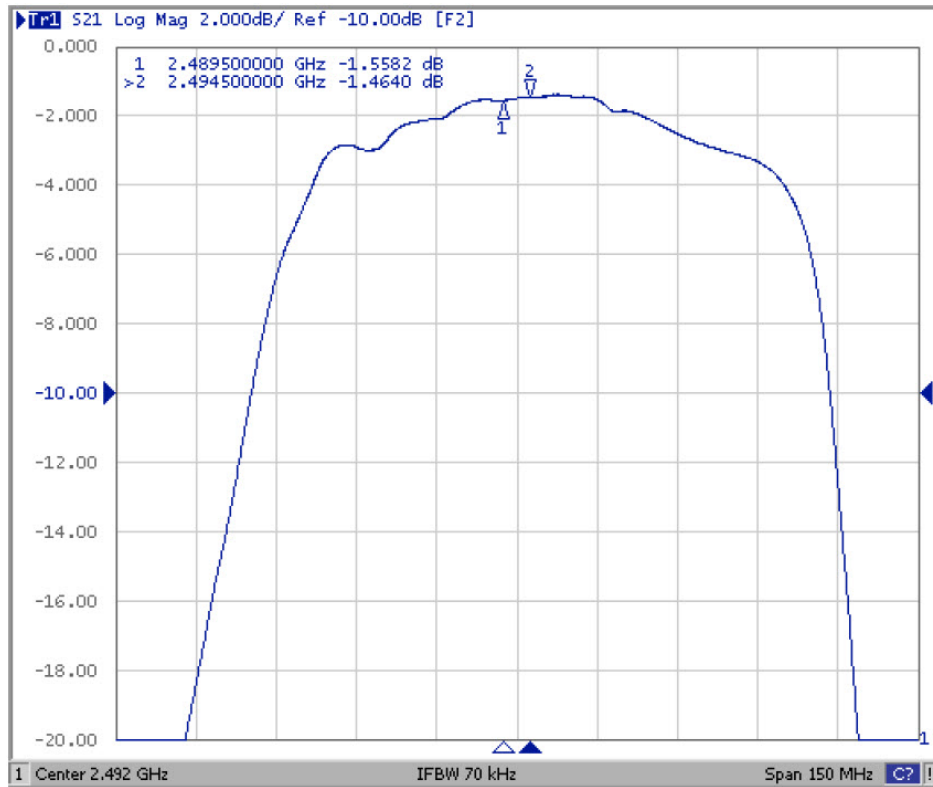


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

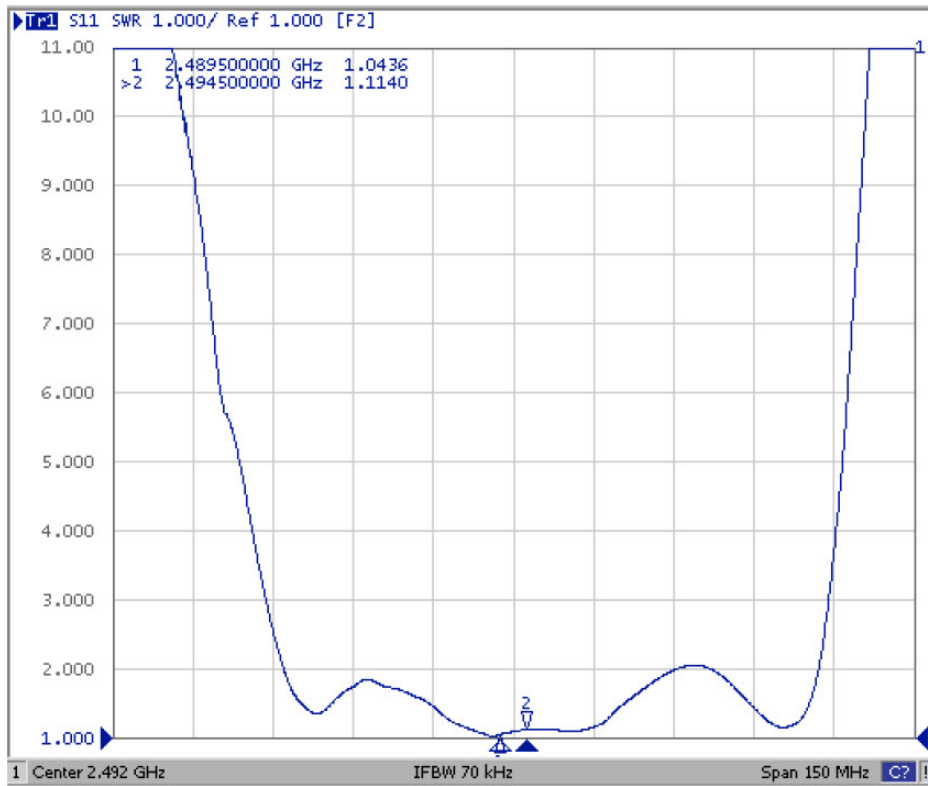
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

# Frequency Characteristics

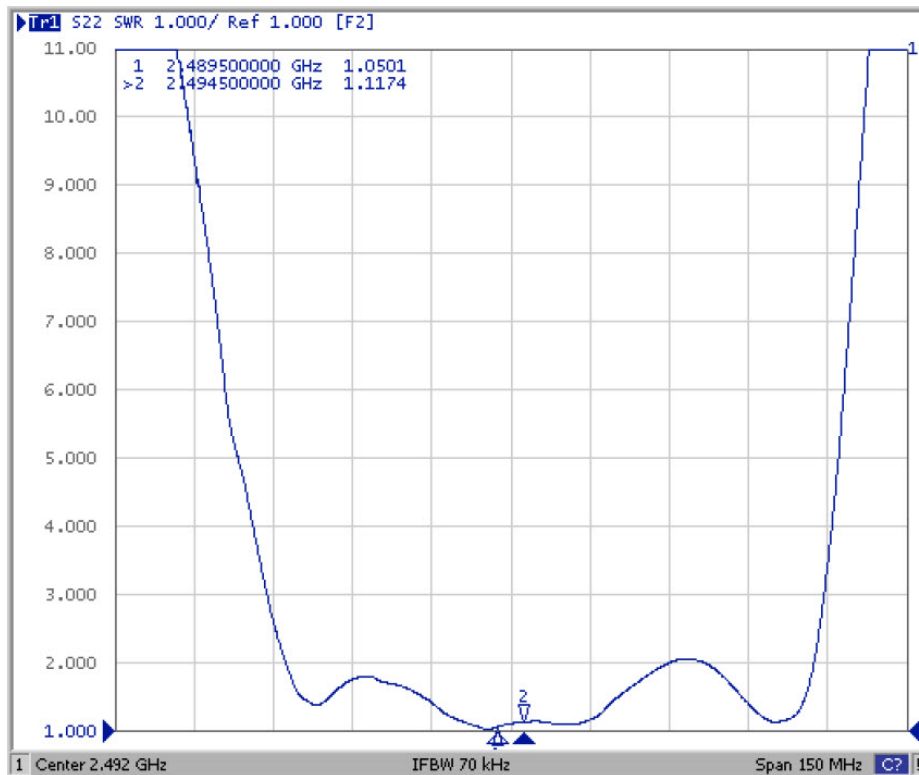


# Reflection Functions

## S11

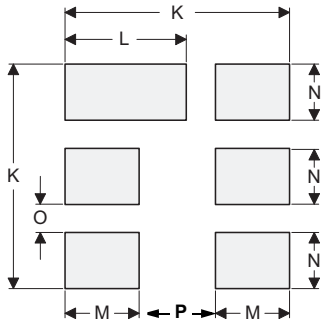
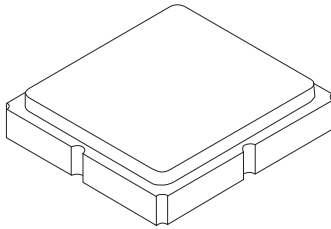


## S22



# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

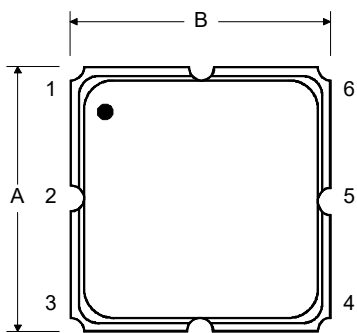
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	-	-	1.40	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-
P	-	1.09	-	-	0.039	-

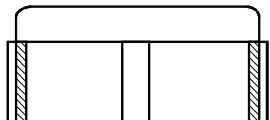
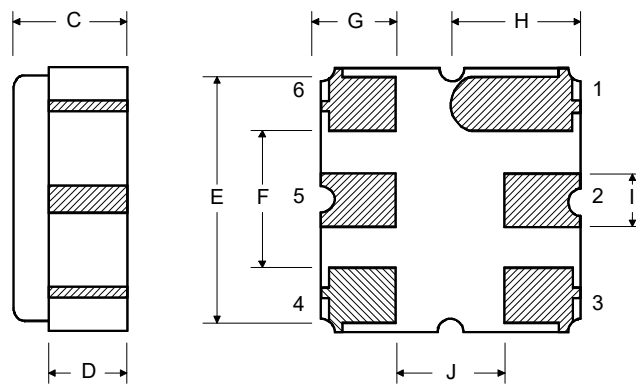
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic
Pb Free	

### TOP VIEW

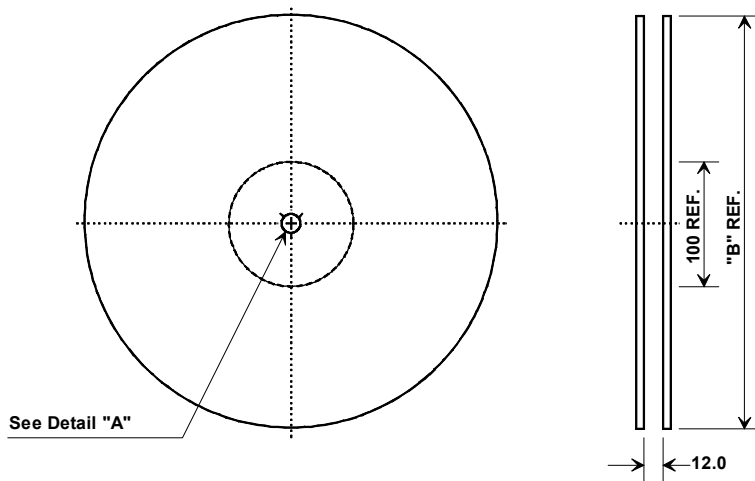


### BOTTOM VIEW

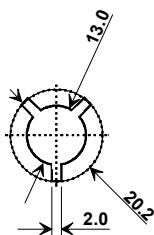


## Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA481

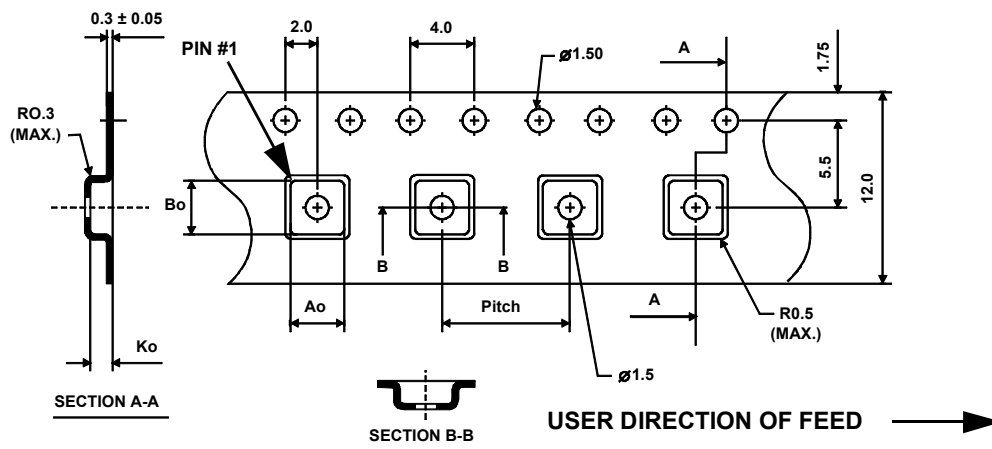


"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



### COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 ±0.1 mm
Bo	3.35 ±0.1 mm
Ko	1.40 ±0.1 mm
Pitch	8.0 ±0.05 mm
W	12.0 ±0.3 mm



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

